

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:  
Maloney, et al.

Serial No. *to be assigned*  
Filed: *herewith*

**Apparatus And Method For Chemical-Mechanical Polishing (CMP) Head Having Direct Pneumatic Wafer Polishing Pressure**

Atty. Docket No.: A-68359-1/RMA

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By *[Signature]*  
Darryl Kriner

**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Washington D.C. 20231  
Box Amendment

Sir:

Please amend the application as follows:

**IN THE CLAIMS**

Please add the following claims:

— 9. (New) A workpiece tooling head for polishing or planarizing a workpiece on a polishing pad, said polishing head comprising:

a retaining ring having an interior cylindrical surface and defining an interior cylindrical pocket sized to carry said workpiece and to laterally restrain movement of said workpiece when said workpiece is moved relative to said polishing pad while being polished against said polishing pad, said retaining ring having a lower surface that is pressed against said polishing pad by a first pressurized fluid to define a first pressure zone of said retaining ring against said polishing pad during polishing of said workpiece; and